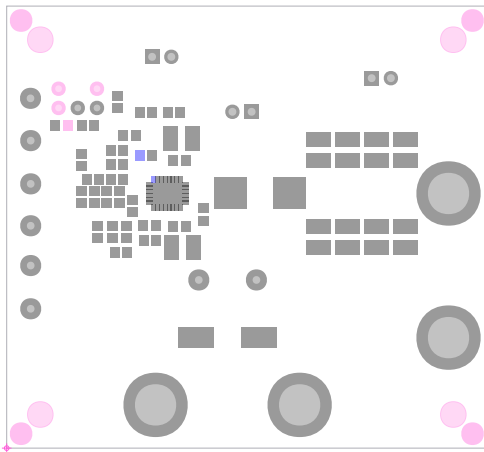


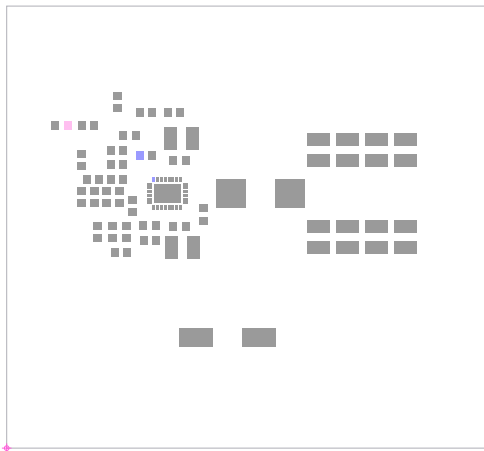
ASSEMBLY TOP

RENESAS
12/16/2019
RTKA211650DE0000BU_C



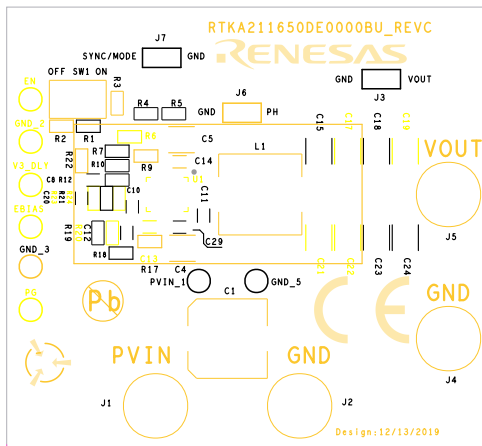
SOLDER MASK TOP

RENESAS
12/16/2019
RTKA211650DE0000BU_C



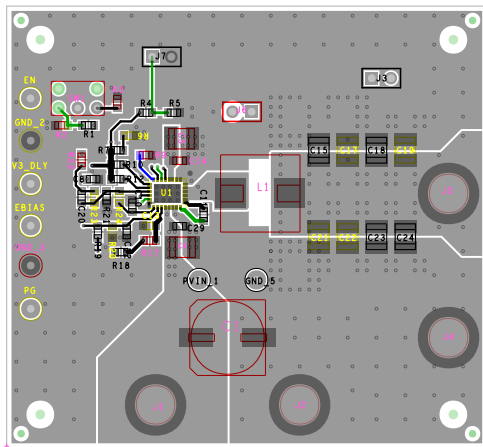
SOLDER PASTE TOP

RENESAS
12/16/2019
RTKA211650DE0000BU_C



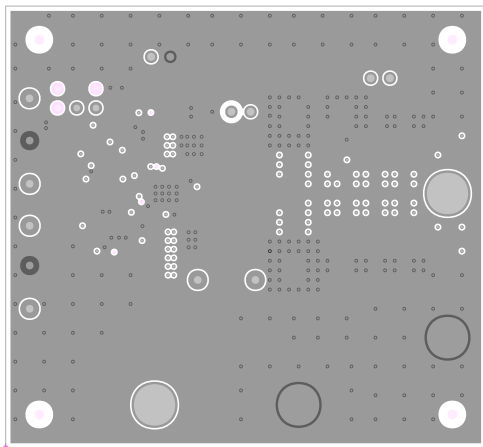
SILK SCREEN TOP

RENEASAS
12/16/2019
RTKA211650DE0000BU_C



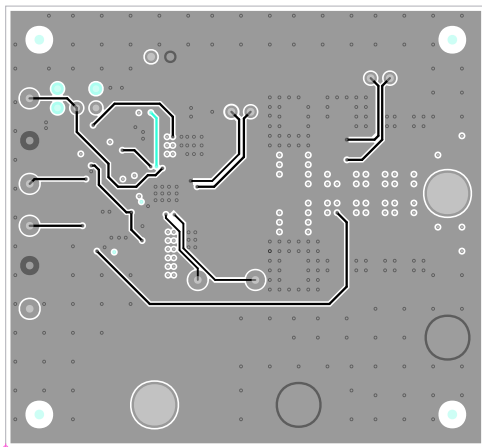
ASSEMBLY TOP COMPONENT SIDE

RENASAS
12/16/2019
RTKA211650DE0000BU_C



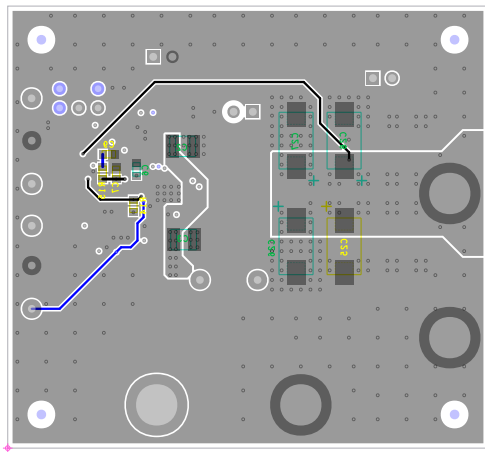
LAYER 2

RENESAS
12/16/2019
RTKA211650DE0000BU_C



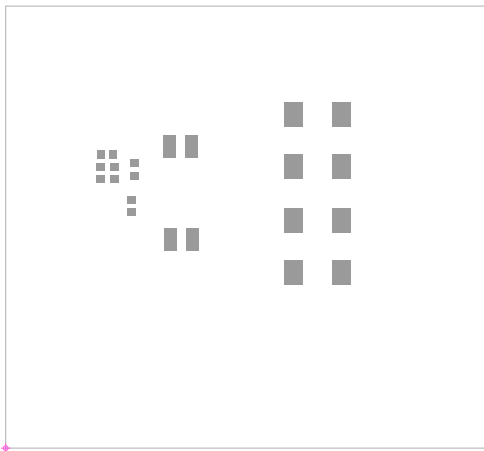
LAYER 3

RENESAS
12/16/2019
RTKA211650DE0000BU_C



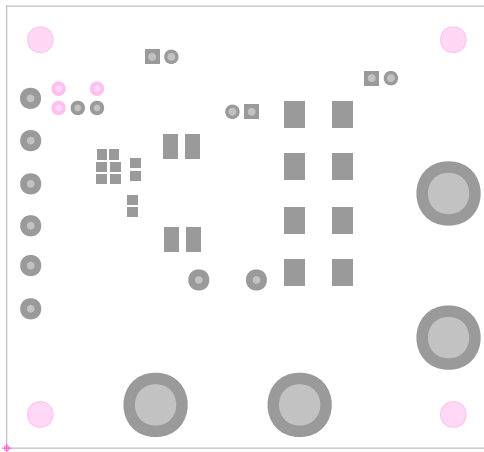
ASSEMBLY BOTTOM SIDE

RENESAS
12/16/2019
RTKA211650DE0000BU_C



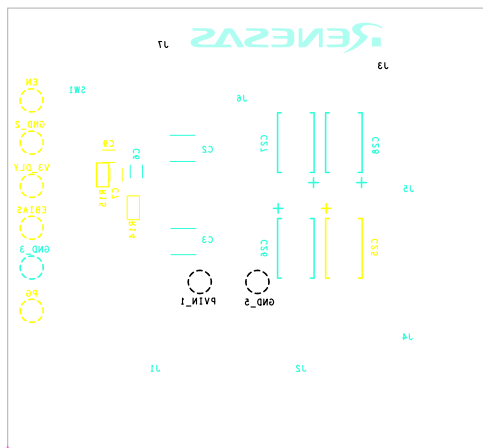
SOLDER PASTE BOTTOM

RENESAS
12/16/2019
RTKA211650DE0000BU_C



SOLDER MASK BOTTOM

RENESAS
12/16/2019
RTKA211650DE0000BU_C

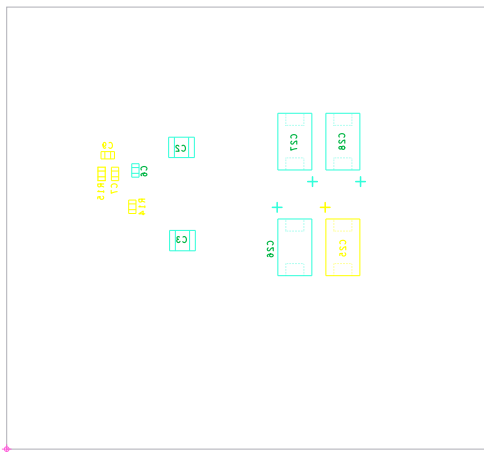


SILK SCREEN BOTTOM

RENEASAS

12/16/2019

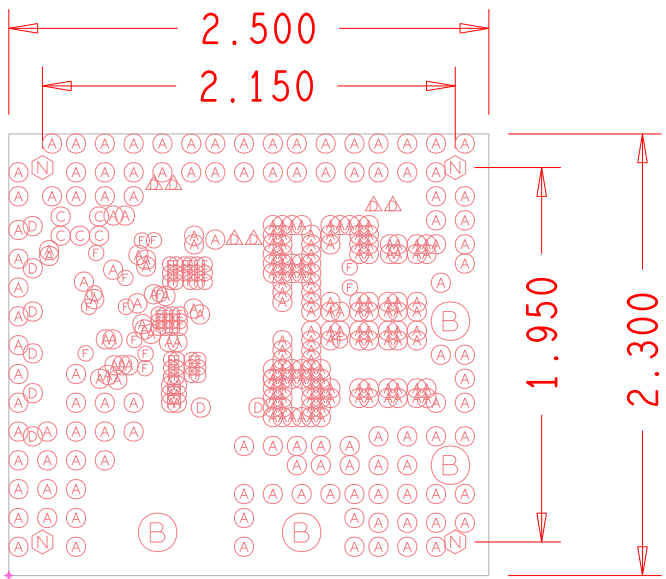
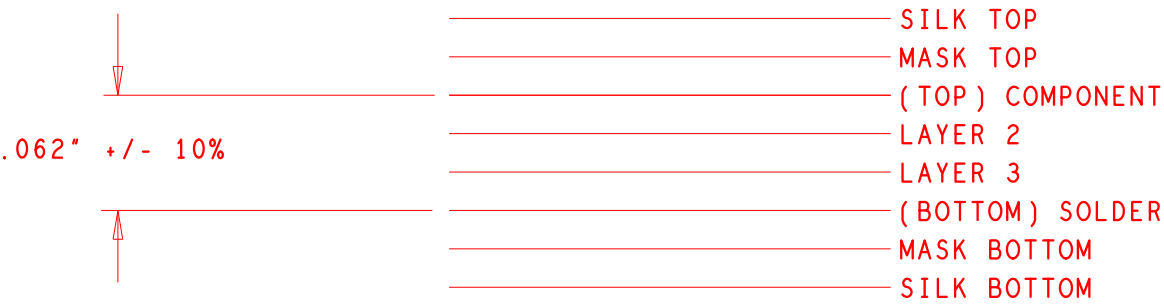
RTKA211650DE0000BU_C



ASSEMBLY BOTTOM

RENESAS
12/16/2019
RTKA211650DE0000BU_C

PHYSICAL BOARD DIMENSIONS



DRILL

DRILL CHART: TOP to BOTTOM
ALL UNITS ARE IN MILS

FIGURE	SIZE	PLATED	QTY
Ⓐ	10.0	PLATED	278
Ⓔ	11.0	PLATED	56
Ⓒ	35.0	PLATED	5
Ⓓ	40.0	PLATED	8
Ⓐ	41.0	PLATED	6
Ⓑ	215.0	PLATED	4
Ⓝ	128.0	NON-PLATED	4

NOTES:

1. THIS BOARD IS RoHS COMPLIANT.
2. PRINTED WIRING BOARD DESIGN AND ACCEPTANCE CRITERIA SHALL BE IAW WITH THE REQUIREMENTS OF IPC-D-275 AND IPC-A-600.
3. MATERIAL: FR4 (RoHS COMPLIANT), 1_OZ COPPER INNER LAYERS AND 2_OZ OUTER LAYERS
4. APPLY SOLDER MASK, BOTH SIDES OVER BARE COPPER IAW IPC-SM-840. CLASS 2 (LPI) (BLUE MASK).
5. ALL PATTERNS ARE VIEWED FROM THE PRIMARY SIDE LOOKING THROUGH THE BOARD.
6. UNLESS OTHERWISE SPECIFIED ALL HOLE DIAMETERS ARE AFTER PLATING.
7. APPLY SILKSCREEN USING WHITE NON-CONDUCTIVE EPOXY BASED INK.
8. PWB MUST BE 100% ELECTRICALLY TESTED FOR SHORTS AND CONTINUITY. USE NETLIST PROVIDED RTKA211650D00000BU-A_IPC356.IPC IAW IPC-D-356.
9. MARK DATE CODE AND MANUFACTURES IDENTIFICATION ON SOLDER SIDE PER IPC-6011 AND IPC-6012.
10. TOLERANCE ON ALL DRILL HOLES SHALL BE IAW IPC-D-2221 & 2222 UNLESS OTHERWISE SPECIFIED.
11. ALL 11 MIL VIA'S ARE TO BE THERMAL EPOXY FILLED AND CAPPED.
12. WAIVE IPC610 SPEC FOR SOLDER FILL VIA (VIA-IN-PAD).
13. ALL VIAS TO BE TENTED. NO EXPOSED COPPER PADS ON ANY VIAS TOP OR BOTTOM EXCEPT VIAS IN SMT PADS.

Drawn By: AMNAT YAKAMNA	Date Drawn: 12/16/2019	Engineer: KRISHNA MAINALI		
Released By:	Date Released:	RAA211650 EVAL BOARD PCB LAYOUT		
Updated By:	Date Updated:			
		MASK#	HDWR ID	REV. C
		FILENAME: RTKA211650DE0000BU_C_12_16_2019		SHEET 1 of 1